

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6646623

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HANG LIU	04/01/2021
WEN-SHAN WANG	04/01/2021
CHIEN-I CHOU	04/01/2021
KIAT-SENG YEO	04/01/2021
RECEIVING PARTY DATA	
Name:	REALTEK SEMICONDUCTOR CORPORATION
Street Address:	NO. 2, INNOVATION ROAD II, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	Taiwan ROC
Postal Code:	300
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17225549
CORRESPONDENCE DATA	
Fax Number:	(703)880-7487
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	703-639-0151
Email:	assignment@WPAT.COM
Correspondent Name:	WPAT, PC INTELLECTUAL PROPERTY ATTORNEYS
Address Line 1:	8230 BOONE BLVD, SUITE 405
Address Line 4:	VIENNA, VIRGINIA 22182
ATTORNEY DOCKET NUMBER:	16313-345
NAME OF SUBMITTER:	JUSTIN KING
SIGNATURE:	/Justin King/
DATE SIGNED:	04/08/2021
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, I(we), HANG LIU, WEN-SHAN WANG, CHIEN-I CHOU and KIAT-SENG YEO whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful invention entitled.

Power amplification apparatus and method having digital pre-distortion mechanism

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent /Utility Patent is executed on even date herewith unless at least one of the following is checked:

- United States Design Patent was
 executed on:
 filed on: Serial No.:
 established by PCT International Patent Application No.: filed: designating the
 United States of America
 issued on _____ as U.S. Patent No.: _____

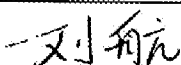
WHEREAS, **REALTEK SEMICONDUCTOR CORPORATION** whose post office address is **No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)** hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States and its territorial possessions;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application for the full term or terms for which the same may be granted, including all priority rights under any International Convention.

ASSIGNOR further covenants that no assignments, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment;

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance, litigation and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

ASSIGNOR NAME HANG LIU	Address 279 Tampines St 22, #05-220, Singapore 520279
Signature of Assignor 	Date of Signature April 1, 2021
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

ASSIGNOR NAME WEN-SHAN WANG <i>Wang Wen-shan</i>	Address No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)
Signature of Assignor <i>Wang Wen-Shan</i>	Date of Signature April 1, 2021
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

ASSIGNOR NAME CHIEN-I CHOU	Address No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)
Signature of Assignor <i>Chien-I Chou</i>	Date of Signature April 1, 2021
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

ASSIGNOR NAME KIAT-SENG YEO	Address 1 SENGKANG EAST AVENUE, #03-01 RIVERSOUND RESIDENCE, SINGAPORE 544811
Signature of Assignor <i>Kiat Seng Yeo</i>	Date of Signature April 1, 2021
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)